

60V N-Channel Trench MOSFET

General Description

- Trench Power SGT technology
- Very low on-resistance R_{DS(ON)}
- Low Gate Charge
- Excellent Gate Charge x R_{DS(ON)} Product

Applications

• High Frequency Switching and Synchronous Rectification

Product Summary

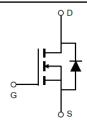
 $\begin{aligned} &V_{DS} & 60V \\ &I_{D} \text{ (at } V_{GS} \text{=} 10V) & 45A \\ &R_{DS(ON)} \text{ (at } V_{GS} \text{=} 10V) & < 15 \text{m}\Omega \end{aligned}$

 $R_{DS(ON)}$ (at V_{GS} =4.5V) < 19m Ω

100% UIS Tested







Part Number	Package Type	Form	Marking
TSU10N06AT	TO-251	Tube	U10N06AT

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

5					
Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current B	T _C =25°C],	45	٨	
	T _C =100°C	ID	27	A	
Pulsed Drain Current A		I _{DM}	180	Α	
Avalanche Current A		I _{AS}	20	Α	
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	20	mJ	
Power Dissipation ^C	T _C =25°C	P _D	56.5	W	
	T _C =100°C		35.7	W	
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 175	°C	
Thermal Characteristics					

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	2.1	00.004	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	50	°C/W	



				Value			
Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC PA	RAMETERS	_ L					
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250µA,V _{GS} =0V		60			V
	7 0 1 1/1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	V 99V V 9V	T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} =60V, V_{GS} =0V	T _J =125°C			100	
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	•			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1.1		2.5	V
D	Otatia Duniu Caruna Ca Daniatana	V _{GS} =10V, I _D =20A			12	15	mΩ
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5V, I_D = 20A$			15	19	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A			100		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V				1	V
I _s	Maximum Body-Diode Continuous Curre	ent ^B				30	Α
DYNAMIC I	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f =1MH _Z			1134		
C _{oss}	Output Capacitance				123		pF
C _{rss}	Reverse Transfer Capacitance				12		
SWITCHING	G PARAMETERS						
Q _g (10V)	Total Gate Charge				21		
Q _g (4.5V)	Total Gate Charge	$V_{GS} = 10V, V_{DS} = 30V, I_{D} = 20A$			11		nC
Q_{gs}	Gate Source Charge				3.1		
Q_{gd}	Gate Drain Charge				5.1		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 30V, I_{D} = 20A,$ $R_{G} = 3\Omega$			7		
t _r	Turn-On Rise Time				3		
$T_{D(off)}$	Turn-Off Delay Time				20		ns
t _f	Turn-Off Fall Time				3		
t _{rr}	Body Diode Reverse Recovery Time				17		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt =500A/μs			60		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

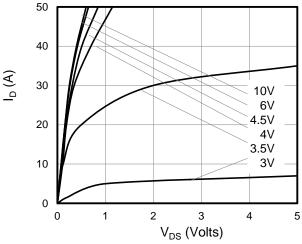


Figure 1: On-Region Characteristics

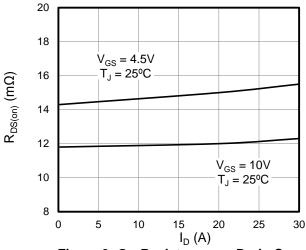


Figure 3: On-Resistance vs. Drain Current

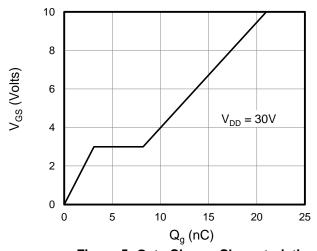


Figure 5: Gate Charge Characteristics

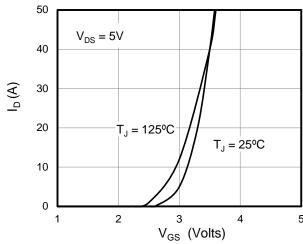


Figure 2: Transfer Characteristics

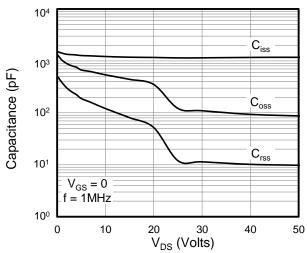


Figure 4: Capacitance Characteristics

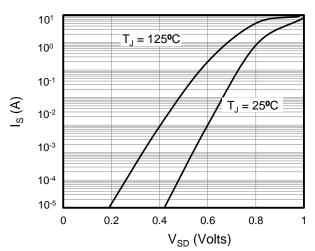
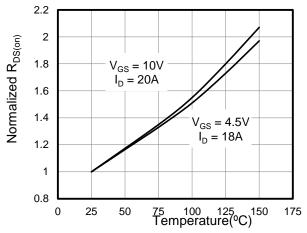


Figure 6: Body Diode Forward Voltage

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



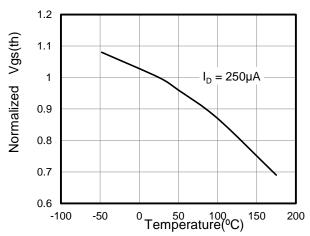
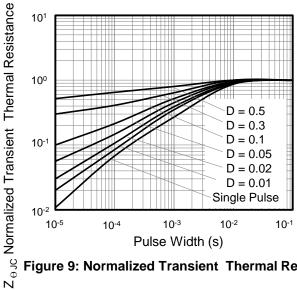


Figure 7: On-Resistance vs. Junction Temperature

Figure 8: Vgs(th) vs. Junction Temperature



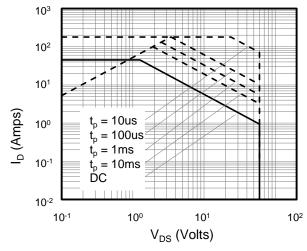


Figure 9: Normalized Transient Thermal Resistance

Figure 10: Safe Operating Area



Figure A: Gate Charge Test Circuit and Waveform

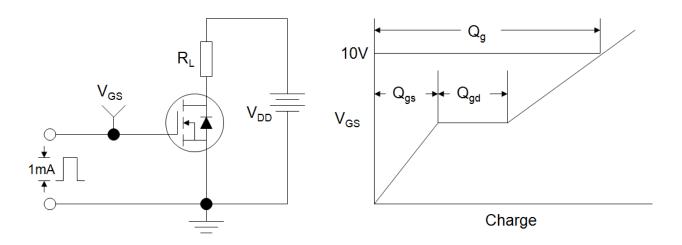


Figure B: Resistive Switching Test Circuit and Waveform

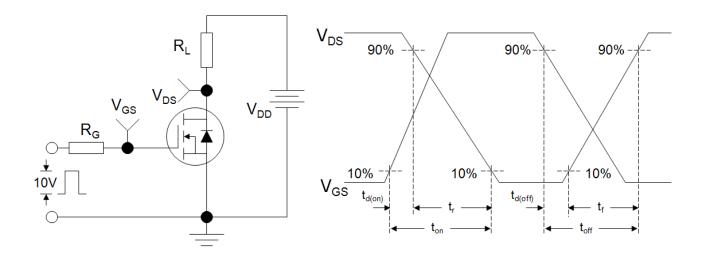
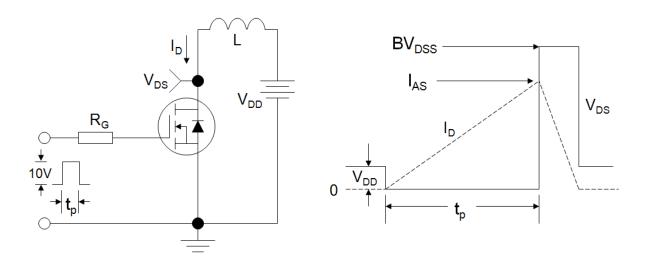
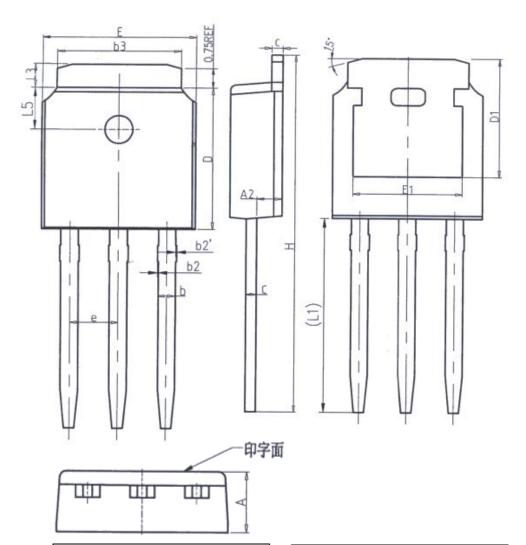


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-251



Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b2	0.00	0.10		
b2′	0.00	0.10		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		

Unit: mm				
Symbol	Min.	Max.		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	-		
е	2. 286BSC			
Н	16. 22	16. 82		
L1	9. 15	9. 65		
L3	0.88	1. 28		
L5	1. 65	1. 95		



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